

AMENDMENTS TO THE SPECIFICATION

Please insert the following paragraph at page 1, line 3:

CROSS-REFERENCE TO RELATED APPLICATIONS

The present application is a continuation of PCT application PCT/CA02/01366 filed on September 10, 2002 designating the United States of America and currently pending, which also claims priority of US provisional application number 60/317,969, filed on September 10, 2001.

Please replace the paragraph at page 8, line 14 with the following amended paragraphs:

According to a fourth broad aspect of the present invention, there is provided a circuit for trimming a functional resistor, the circuit comprising: ~~a thermally-isolated micro-platform on a substrate~~; a plurality of functional resistors spaced apart on the ~~thermally-isolated micro-platform~~ ~~thermally-isolated~~ on a substrate; and trimming circuitry for subjecting a portion of the ~~thermally-isolated micro-platform~~ ~~substrate~~ to heat pulses such that a resistance value of one of said plurality of functional resistors is trimmed while a resistance value of remaining ones of said plurality of functional resistors remains substantially untrimmed.

Preferably, the circuit comprises a thermally-isolated micro-platform on the substrate and the plurality of functional resistors are placed on the thermally-isolated micro-platform.

Please replace the paragraph at page , line 23 with the following amended paragraphs:

According to a fifth broad aspect of the present invention, there is provided a circuit for trimming circuit elements, the circuit comprising: ~~at least one thermally-isolated micro-platform on a substrate~~; at least two resistive elements with non-zero temperature induced drift on said at least one thermally-isolated micro-platform ~~thermally isolated on a substrate~~, such that said at least two resistive

elements ~~on said at least one micro-platform~~ are subjected to a substantially same operating environment, at least one of said at least two resistive elements ~~on said at least one micro-platform~~ being thermally trimmable; and trimming circuitry for thermally trimming said at least one of said at least two resistive elements; wherein said at least two resistive elements are connected together in said circuit in a manner to compensate for said operating environment ~~on said at least one micro-platform~~, and heat generated ~~on the at least one micro-platform~~ is distributed among the at least two circuit elements such that an effect of temperature drift is compensated.

Preferably, at least one thermally-isolated micro-platform is provided and the at least two resistive elements are placed on the thermally-isolated micro-platform.

Please replace the paragraph at page 9, line 6 with the following amended paragraphs:

According to a sixth broad aspect of the present invention, there is provided a circuit for trimming a functional resistor, the circuit comprising: ~~a thermally-isolated micro-platform on a substrate~~; a functional resistor on ~~said thermally-isolated micro-platform~~ substrate subject to a heat source having a power dissipation geometry adapted to obtain a substantially constant temperature distribution across said functional resistor when a temperature of said functional resistor is raised for trimming purposes; and trimming circuitry for trimming the functional resistor.

Preferably, the circuit comprises a thermally-isolated micro-platform on the substrate and functional resistor is placed on the thermally-isolated micro-platform.

Please replace the paragraph at page 9, line 23 with the following amended paragraphs:

According to an eighth broad aspect of the present invention, there is provided a circuit for calculating a temperature coefficient of resistance of a functional resistor, the circuit comprising: ~~at least one thermally-isolated micro-platform on a substrate~~; a

functional resistor on said at least one thermally-isolated micro-platform thermally-isolated on a substrate; heating circuitry for heating said functional resistor; measuring circuitry for measuring a resistance value of said functional resistance at ambient temperature and at an elevated temperature; and calculating circuitry for calculating said temperature coefficient of resistance based on said resistance value at ambient temperature and at an elevated temperature.

Preferably, at least one thermally-isolated micro-platform is provided on the substrate and the functional resistor is placed on the at least one thermally-isolated micro-platform.